



DESCRIPTION

EC-326 is a Bisphenol A based acetate/propionate epoxy curative. This low melting curative is ideal for chain extension. It is soluble in most epoxy monomers. The curative provides thermosets with low moisture uptake relative to a phenolic curative. Depending on the epoxy to curative ratios, the properties range from tough thermosets to thermoplastics. The EC-326, unlike phenolic curatives, does not interfere with free-radical cure in hybrid adhesive systems.

HIGHLIGHTS

• Hydrolytically resistant	• Hydrophobic
• Low melting point	• Toughener
• Thermal stability	• Does not impede free-radical cure

TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	METHOD	RESULT
Appearance at Room Temperature	Visual	White/yellow solid
Viscosity at 25°C (typical) - (super cooled liquid)	Haake Rheometer	2,200 cps
Melting Point (typical)	DSC	40 - 45°C
Density		1.12 g/cc
Flash Point	Closed Cup	> 200°C
Functionality		2
Molecular Weight (approx.)		326
Decomposition Temperature (approx.)	TGA	250°C
Recommended Storage Temp		25°C or below

Data is for reference only and may vary depending on testing method used. The structure shown above is an idealized representation of a statistical distribution.

RECOMMENDED FORMULATION USE:

EC-326 is recommended for use as an epoxy curative to improve toughness, hydrophobicity, and hydrolytic stability. A one-to-one equivalent ratio of EC-326 to a difunctional epoxy will (depending on the catalyst used) cure to a thermoplastic resin. To form a thermoset, a twenty equivalent percent excess, or more, of epoxy is recommended. Standard epoxy catalysts such as amines, imidizoles, and Lewis acids work well to cure the EC-326 with epoxy resins.

CONTACT:

REQUEST A SAMPLE OR PLACE AN ORDER

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